

Nexperia introduces leading edge Silicon Carbide (SiC) Schottky Diodes for ultra-high performance, low loss, and high efficiency power conversion applications. Benefit from temperature independent capacitive turn-off and zero recovery switching behavior combined with an outstanding figure-of-merit ($Q_c \times V_F$). The Merged PN Schottky diode improves the robustness expressed in a high I_{FSM} .

Product range

Qualification	V _{RRM} (V)	I _F (A)	TO-252-2 (DPAK R2P)	TO-263-2 (D2PAK R2P)	TO-220-2	TO-247-2
Automotive and industrial	1200	10	N. J. S.	N. Janes		Se la constant de la
		16				
		20				
	650	6				
		10				
		16				
		20				

650 V, 10 A industrial grade PSC1065H/K in four high-voltage compliant real 2-pin (R2P) packages with higher creepage distance available now.



Key features

- Zero forward and reverse recovery
- > Temperature independent switching performance
- > Fast and smooth switching performance
- > High I_{FSM} capability
- > Low leakage current
- > Easy to parallel / positive temperature coefficient
- > Outstanding figure-of-merit (Q x V)
- > Thermal stability up to 175 °C junction temperature
- > AEC-Q101 qualification

Key benefits

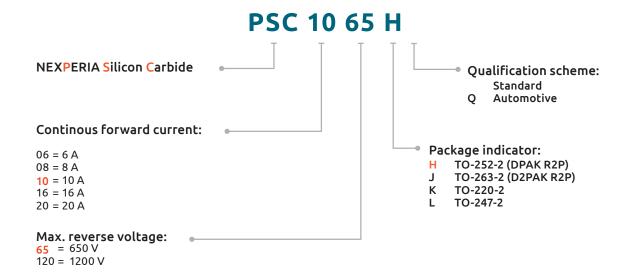
- > High power density
- > Reduced system cost
- System miniaturization
- > High temperature operation
- > Reduced EMI
- Increased ruggedness and reliability

Key applications

- Consumer and industrial power supplies / PFC
- > DC-DC-converter
- High frequency AC-DC converter
- > Traction inverter
- On board charger
- > Battery charging systems
- > Base station power supply (5G)
- > Photovoltaic power converter



Demonstrator sample pack with 650 V, 10 A SiC Schottky Diodes



Full portfolio with 72 parts will be launched in 2022.

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